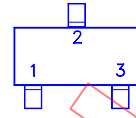
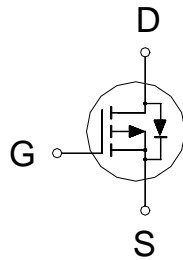


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
-30	64m	-4A



1 :GATE
2 :DRAIN
3 :SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	-30	V
Gate-Source Voltage		V_{GS}	± 12	V
Continuous Drain Current	$T_C = 25\text{ }^\circ\text{C}$	I_D	-4	A
	$T_C = 70\text{ }^\circ\text{C}$		-3	
Pulsed Drain Current ¹		I_{DM}	-20	
Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	P_D	1.25	W
	$T_C = 70\text{ }^\circ\text{C}$		0.8	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	$R_{\theta JA}$	75	100	$^\circ\text{C} / \text{W}$

¹Pulse width limited by maximum junction temperature.

²Duty cycle $\leq 1\%$

ELECTRICAL CHARACTERISTICS ($T_C = 25\text{ }^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.45	-0.8	-1.2	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 12V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -24V, V_{GS} = 0V$			-1	μA
		$V_{DS} = -20V, V_{GS} = 0V, T_J = 125\text{ }^\circ\text{C}$			-10	
On-State Drain Current ¹	$I_{D(ON)}$	$V_{DS} = -5V, V_{GS} = -4.5V$	-20			A
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = -1.8V, I_D = -2A$		90	120	m
		$V_{GS} = -2.5V, I_D = -3A$		62	80	
		$V_{GS} = -4.5V, I_D = -4A$		55	64	
Forward Transconductance ¹	g_{fs}	$V_{DS} = -5V, I_D = -4A$		12		S

DYNAMIC					
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = -15V, f = 1MHz$		950	pF
Output Capacitance	C_{oss}			115	
Reverse Transfer Capacitance	C_{rss}			75	
Total Gate Charge ²	Q_g	$V_{DS} = 0.5V_{(BR)DSS}, V_{GS} = -4.5V,$ $I_D = -4A$		9.4	nC
Gate-Source Charge ²	Q_{gs}			2	
Gate-Drain Charge ²	Q_{gd}			3	
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DD} = -10V$ $I_D \cong -1A, V_{GS} = -4.5V, R_G = 6$		6.3	nS
Rise Time ²	t_r			3.2	
Turn-Off Delay Time ²	$t_{d(off)}$			38	
Fall Time ²	t_f			12	
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_c = 25^\circ C$)					
Continuous Current	I_s			-1.6	A
Pulsed Current ³	I_{SM}			-3	
Forward Voltage ¹	V_{SD}	$I_F = -1A, V_{GS} = 0V$		-1.2	V

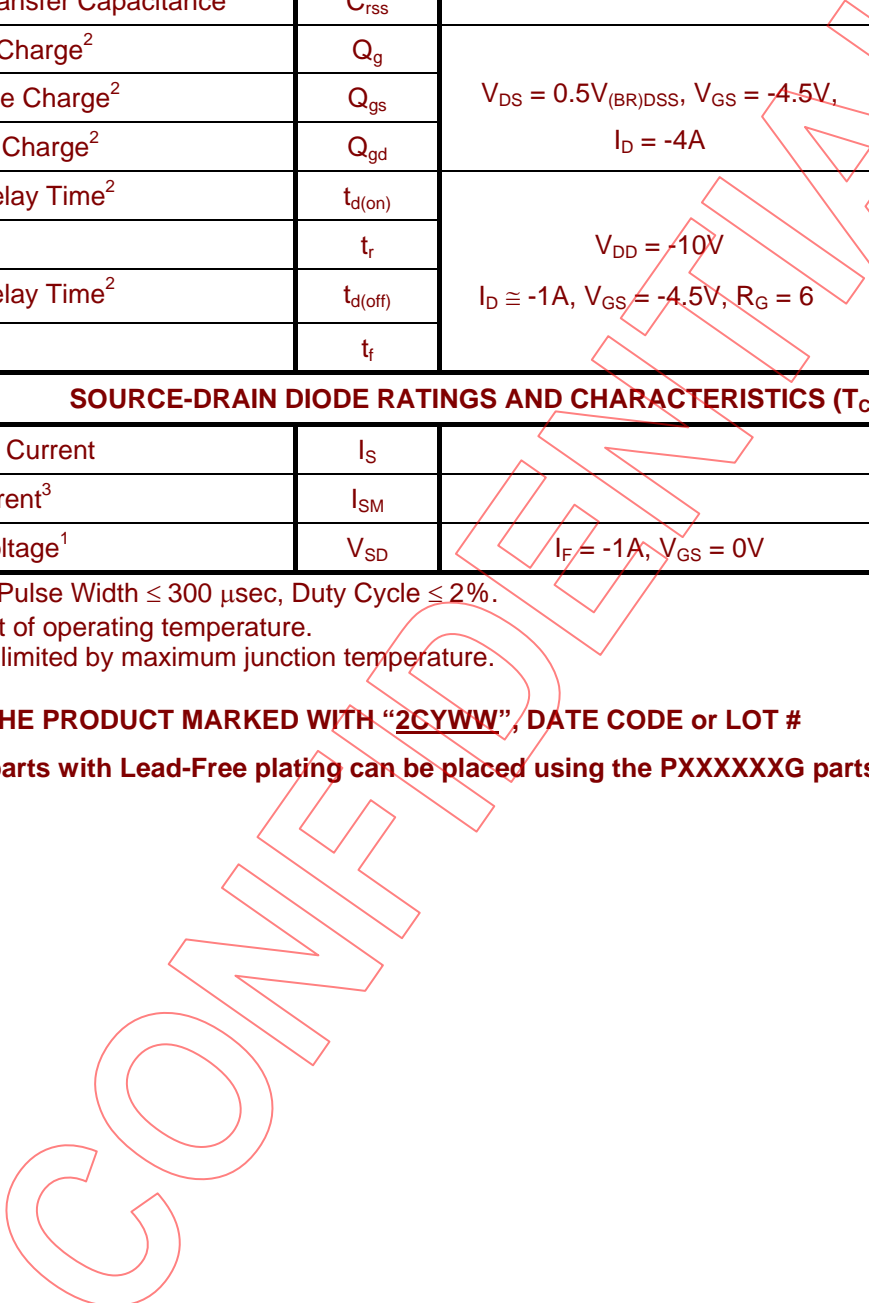
¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

³Pulse width limited by maximum junction temperature.

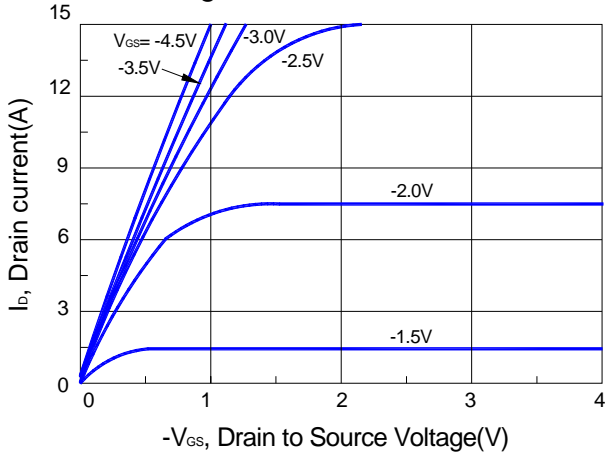
REMARK: THE PRODUCT MARKED WITH "2CYWW", DATE CODE or LOT #

Orders for parts with Lead-Free plating can be placed using the PXXXXXXG parts name.

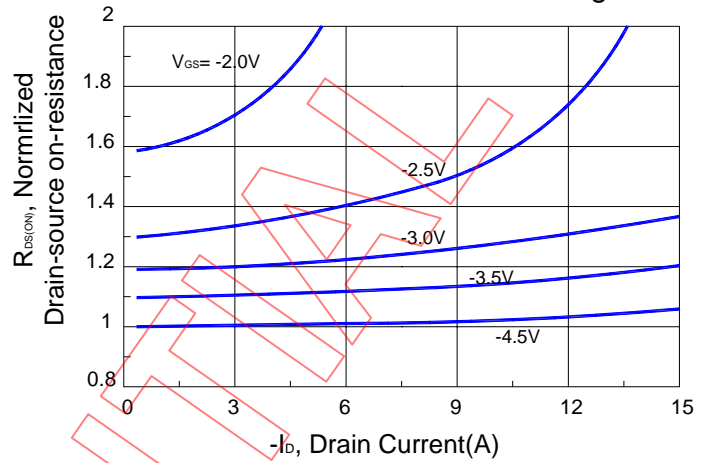


Typical Electrical Characteristics

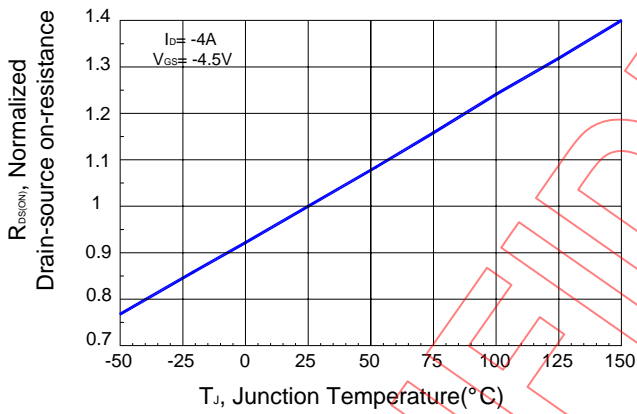
On-Region Characteristics.



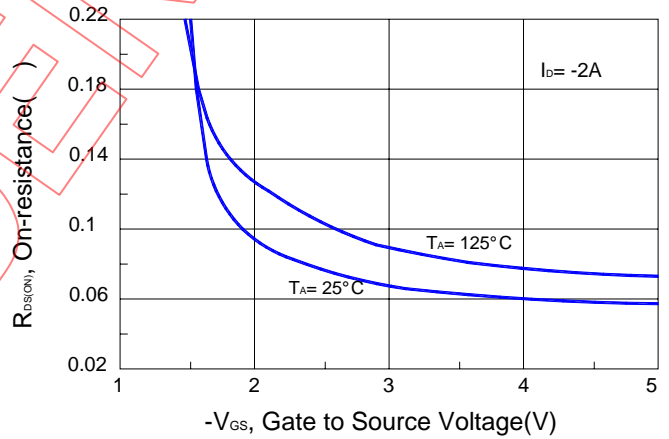
On-Resistance Variation with Drain Current and Gate Voltage.



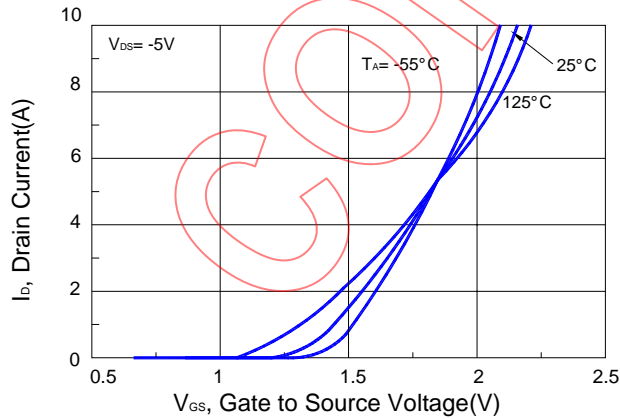
On-Resistance Variation with Temperature.



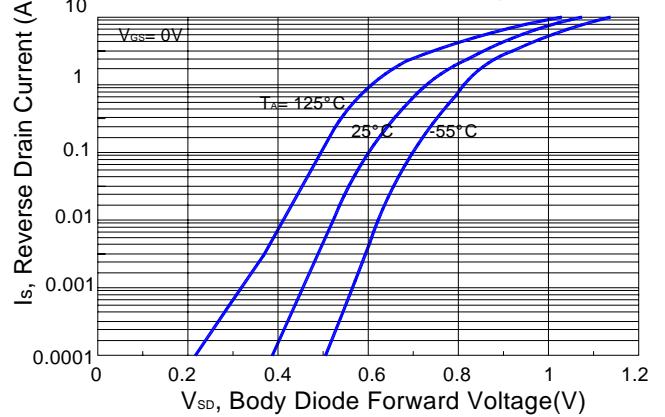
On-Resistance Variation with Gate-to-Source Voltage.



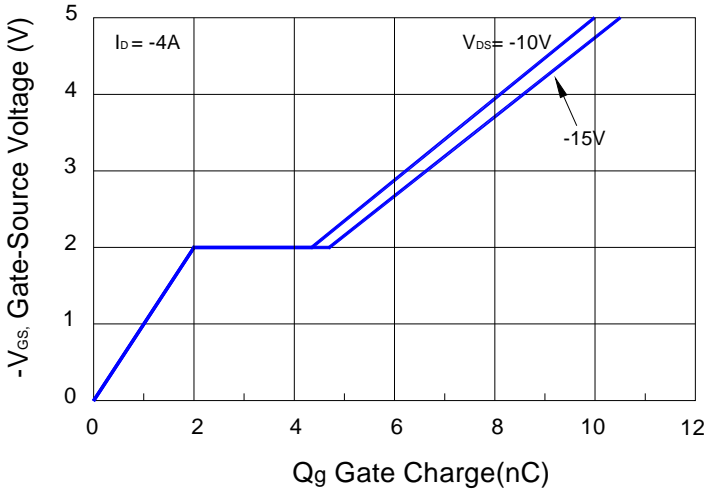
Transfer Characteristics.



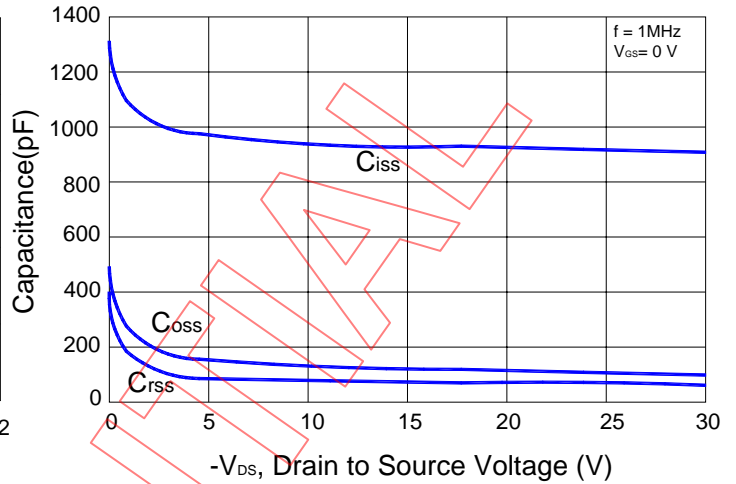
Body Diode Forward Voltage Variation with Source Current and Temperature.



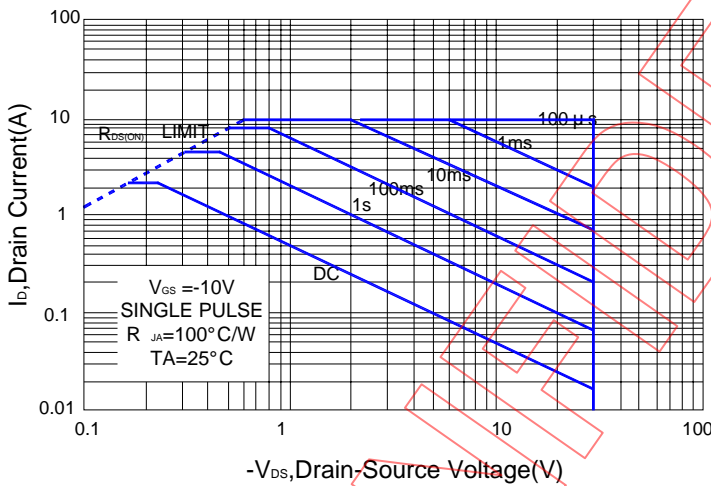
Gate-Charge Characteristics



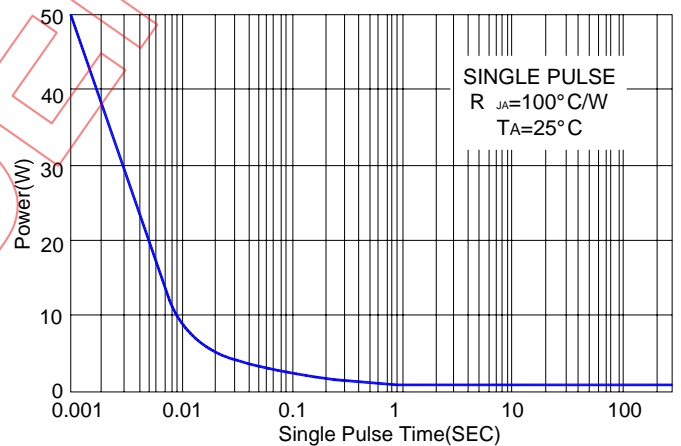
Capacitance Characteristics



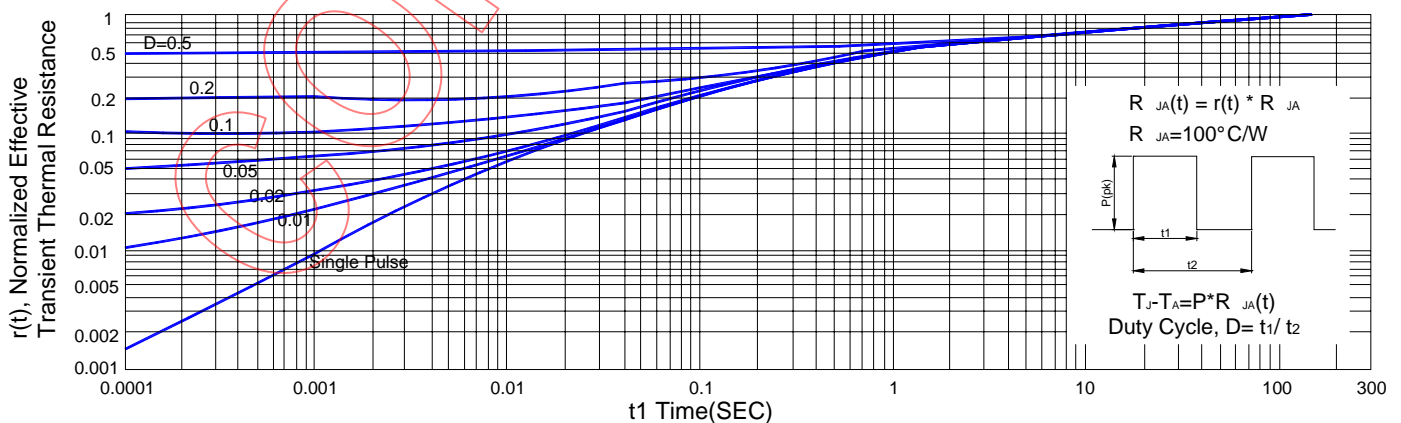
Maximum Safe Operating Area.



Single Pulse Maximum Power Dissipation.



Transient Thermal Response Curve.



SOT-23 (M3) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	0.85	0.95	1.15	H	0.1	0.15	0.35
B	2.4		3	I	0.2		0.6
C	1.4	1.6	1.8	J			
D	2.7	2.9	3.1	K			
E	0.9	1.1	1.4	L			
F	0		0.1	M			
G	0.3	0.4	0.5	N			

